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CAP STYLE		
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PRODUCT NUMBER	NOTES	CONTACT PLATING	SOLDER BALL	CAP STYLE	
74217-001			SnPb	STANDARD	A
74217-001BF	8	Π ",	SnPb	STANDARD	
74217-001LF	5 6	─ 15u" (.38um) Au OVER Ni	SnAgCu LEAD FREE	STANDARD	
74217-001BLF	5 6 8		SnAgCu LEAD FREE	STANDARD	<u> </u>
74217-091			SnPb	STANDARD	
74217-091BF	8	┑	SnPb	STANDARD	<u></u> А
74217-091LF	5 6	15u" (.38um) GXT OVER Ni	SnAgCu LEAD FREE	STANDARD	
74217-091BLF	5 6 8		SnAgCu LEAD FREE	STANDARD	<b>一</b>
74217-093			SnPb	SPECIAL WITH VENT HOLES	
74217-093LF	5 6	15 " ( 70 ) 0)/T 0)/50 )	SnAgCu LEAD FREE	SPECIAL WITH VENT HOLES	
74217-093BF	8	15u" (.38um) GXT OVER Ni	SnPb	SPECIAL WITH VENT HOLES	
74217-093BLF	Ť	7	SnAgCu LEAD FREE	SPECIAL WITH VENT HOLES	
74217-101			SnPb	STANDARD	
74217-101BF	8	30u" (.76um) Au OVER Ni	SnPb	STANDARD	
74217-101LF	5 6		SnAgCu LEAD FREE	STANDARD	
74217-101BLF	5 6 8		SnAgCu LEAD FREE	STANDARD	
74217-191			SnPb	STANDARD	
74217-191BF	8	<b></b>	SnPb	STANDARD	A
74217-191LF	5 6	│ 30u" (.76um) GXT OVER Ni	SnAgCu LEAD FREE	STANDARD	
74217-191BLF	5 6 8	┦ ` ′	SnAgCu LEAD FREE	STANDARD	A
74217-201			SnPb	STANDARD	
74217-201BF	8	1 see Note 1	SnPb	STANDARD	A
74217-201LF	8 5 6	SEE NOTE 4.	SnAgCu LEAD FREE	STANDARD	
74217-201BLF	5 6 8		SnAgCu LEAD FREE	STANDARD	A
74217-291		$\dashv$	SnPb	STANDARD	
74217-291BF	8 5 6	→ SEE NOTE 4.	SnPb	STANDARD	A
74217-291LF			SnAgCu LEAD FREE	STANDARD	
74217-291BLF	568		SnAgCu LEAD FREE	STANDARD	▲

NOTES:

( 1.) <u>MAT'L:</u>

HOUSING: LCP

CONTACT: COPPER ALLOY

**PLATING** 

form: A4mmXLc-2016-02-24

CONTACT: (SEE TABLE ON SHEET1) SOLDER BALL: (SEE TABLE ON SHEET1) EUTECTIC SnPb OR LEAD FREE 95.5Sn/4Ag/0.5Cu

- (2.) SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE DUE TO REFLOW ATTACHMENT.
- (3.)MATED HEIGHT EFFECTED BY CUSTOMER'S PCB PAD SIZE, PLATING, SOLDER REFLOW PROFILE, & SOLDER PASTE.
- (4.) PLATING FOR -2XX SERIES DASH NOS. MEETS THE REQUIREMENTS OF CENTRAL OFFICE ENVIRONMENT, (25 YEAR LIFE EXPECTANCY).
- (5.) FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033 LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE. LEAD FREE PRODUCT IS THERFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI APPLICATION SPECIFICATION

- THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-47-0004 PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN THE LOT CODE NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH CHARACTER POSITION
- VISABLE KNIT LINES ANYWHERE ON THE FLOOR OF THE HOUSING ARE PERMITTED. OPEN KNIT LINES ANYWHERE ARE NOT PERMITTED.
- FOR THESE DASH NUMBERS, PRODUCT IS BERYLLIUM FREE.
  - 9. A /T SYMBOL WILL BE NEXT TO ANY DIMENSION, NEW VIEW OR NOTE WHICH HAS BEEN MODIFIED WITH THE CURRENT DRAWING REVISION

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PDS: Rev :T 3

STATUS:Released

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